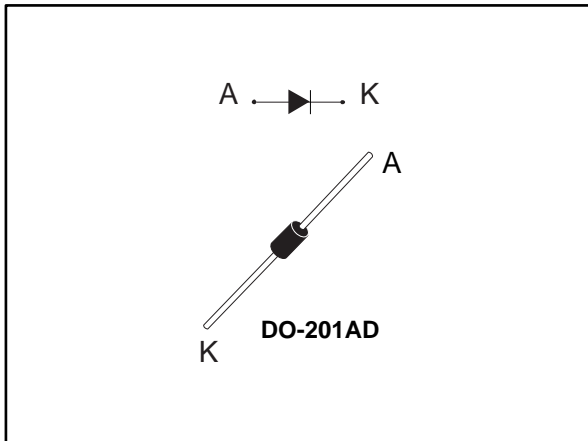


Turbo 2 ultrafast high voltage rectifier

Datasheet - production data



Features

- Ultrafast switching
- Low forward voltage drop
- Low leakage current (platinum doping)
- High operating junction temperature

Description

This device uses ST Turbo 2 600 V technology and is specially suited for use as a boost diode in discontinuous or critical mode power factor correction.

Packaged in DO-201AD it is ideal for use as freewheeling diode in power supplies and other power switching applications.

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	4 A
V_{RRM}	600 V
T_j (max.)	175 °C
V_F (typ.)	0.9 V
t_{rr} (typ.)	40 ns

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward rms current		10	A
$I_{F(AV)}$	Average forward current		4	A
I_{FSM}	Surge non repetitive forward current	$t_p = 8.3$ ms sinusoidal	80	A
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature		175	°C

Table 3: Thermal parameters

Symbol	Parameter		Maximum values	Unit
$R_{th(j-l)}$	Junction to lead	Terminal length = 10 mm	20	°C/W
$R_{th(j-a)}$	Junction to ambient		75	

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25$ °C	$V_R = V_{RRM}$	-	-	3	μA
		$T_j = 150$ °C		-	15	100	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25$ °C	$I_F = 3$ A	-		1.30	V
		$T_j = 150$ °C		-	0.85	1.05	
		$T_j = 150$ °C	$I_F = 4$ A	-	0.90	1.10	

Notes:

(1) Pulse test: $t_p = 5$ ms, $\delta < 2\%$

(2) Pulse test: $t_p = 380$ μs, $\delta < 2\%$

To evaluate the maximum conduction losses, use the following equation:

$$P = 0.92 \times I_{F(AV)} + 0.0045 \times I_{F(RMS)}^2$$

Table 5: Dynamic characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time		$I_F = 1\text{ A}$, $di_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	55	75	ns
			$I_F = 1\text{ A}$, $di_F/dt = -100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	40	55	
I_{RM}	Reverse recovery current	$T_j = 25\text{ °C}$	$I_F = 4\text{ A}$, $di_F/dt = -100\text{ A}/\mu\text{s}$, $V_R = 400\text{ V}$	-	3	4	A
		$T_j = 150\text{ °C}$		-	5	6.5	
t_{fr}	Forward recovery time		$I_F = 4\text{ A}$, $di_F/dt = -100\text{ A}/\mu\text{s}$, $V_{FR} = 1.1 \times V_{Fmax}$	-		130	ns
V_{FP}	Forward recovery voltage		$I_F = 4\text{ A}$, $di_F/dt = 100\text{ A}/\mu\text{s}$	-		7.5	V

1.1 Characteristics (curves)

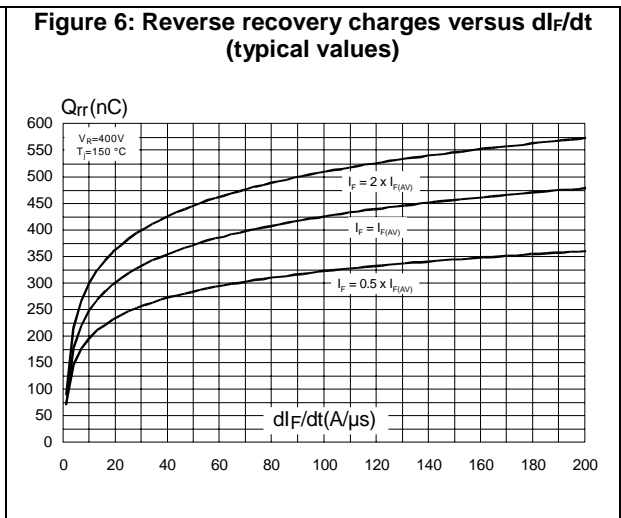
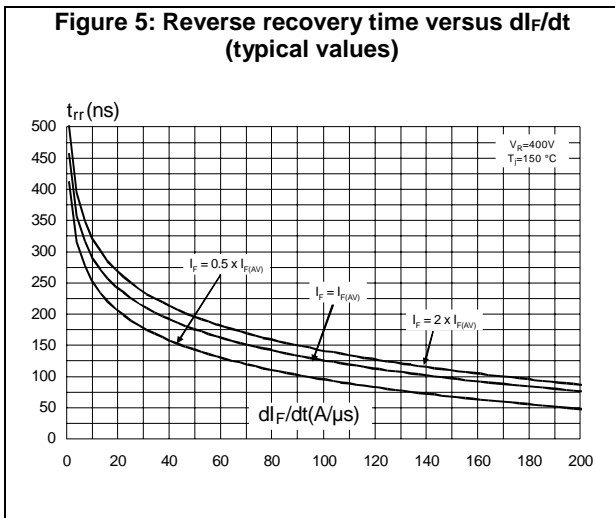
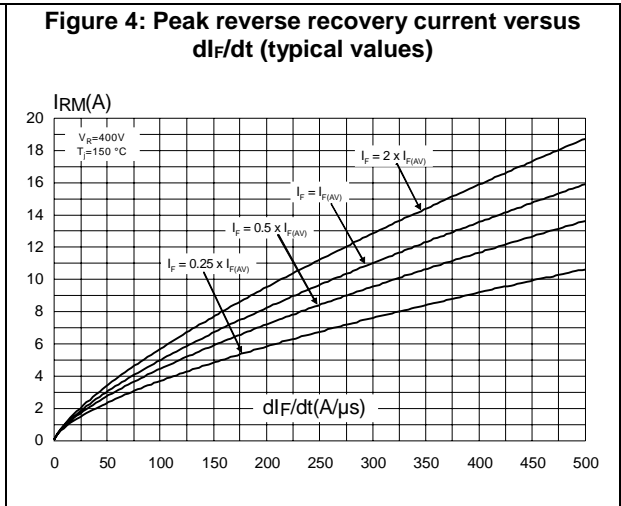
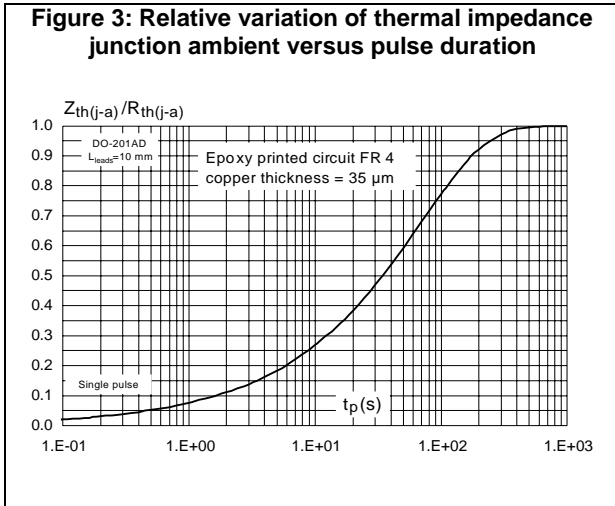
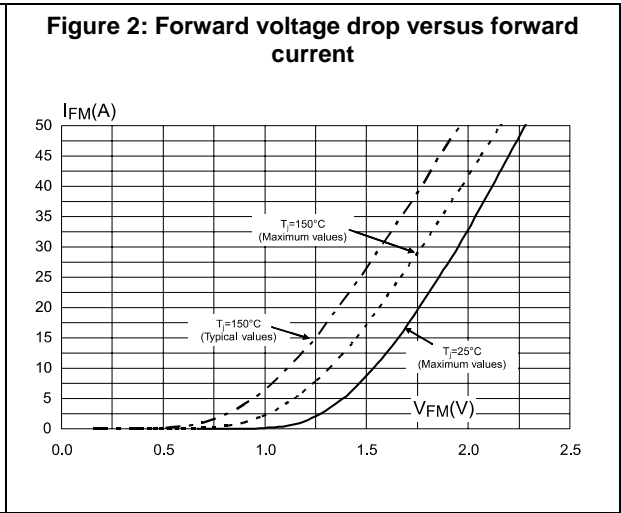
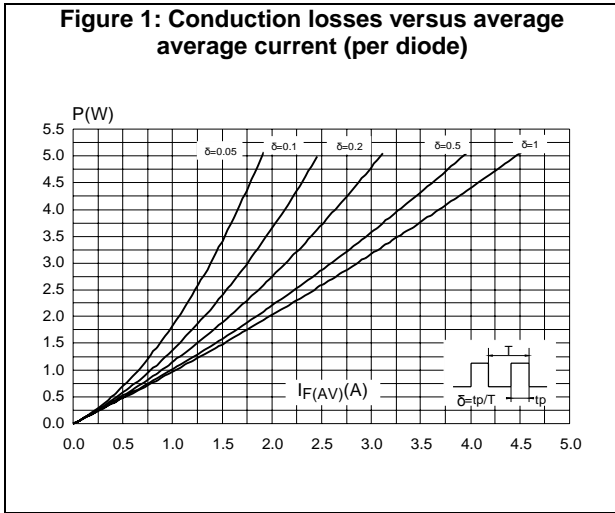


Figure 7: Relative variations of dynamic parameters versus junction temperature

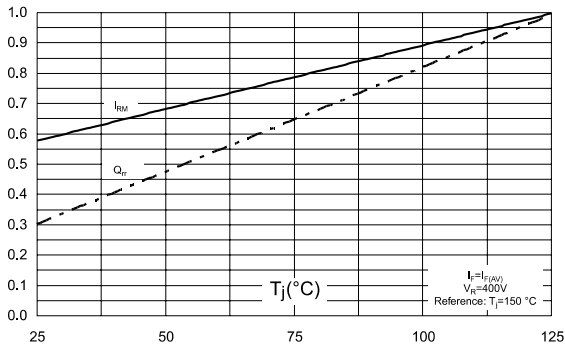


Figure 8: Transient peak forward voltage versus di_F/dt (typical values)

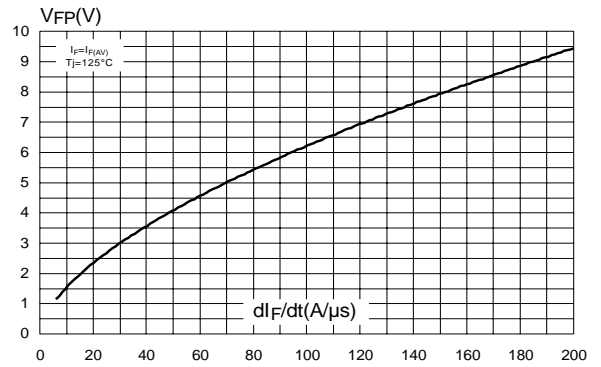


Figure 9: Forward recovery time versus di_F/dt (typical values)

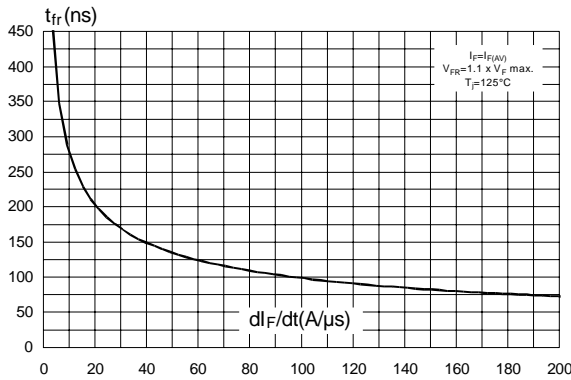


Figure 10: Junction capacitance versus reverse voltage applied (typical values)

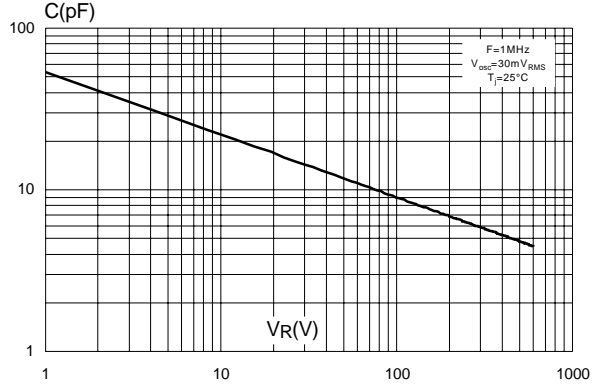


Figure 11: Thermal resistance junction to ambient versus copper surface under lead

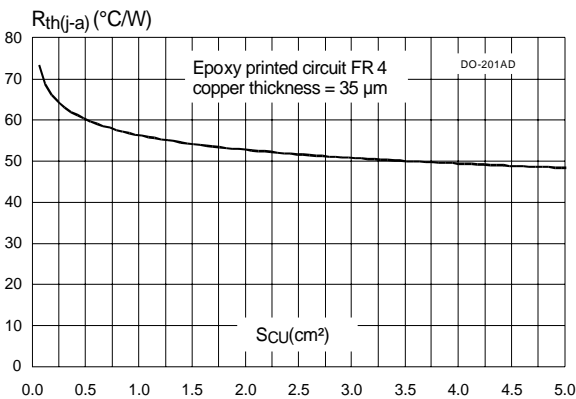
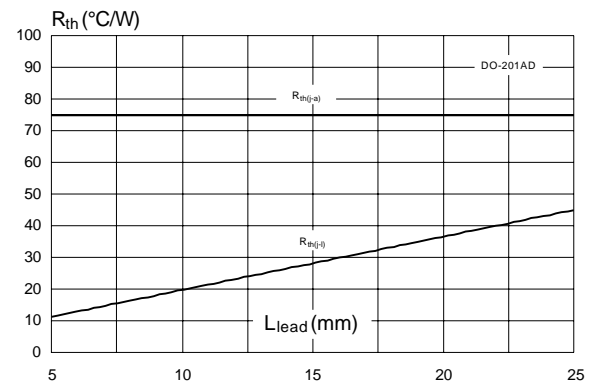


Figure 12: Thermal resistance versus lead length



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Band indicated cathode (DO-201AD)
- Bending method: see application note AN1471 (DO-201AD)

2.1 DO-201AD package information

Figure 13: DO-201AD package outline

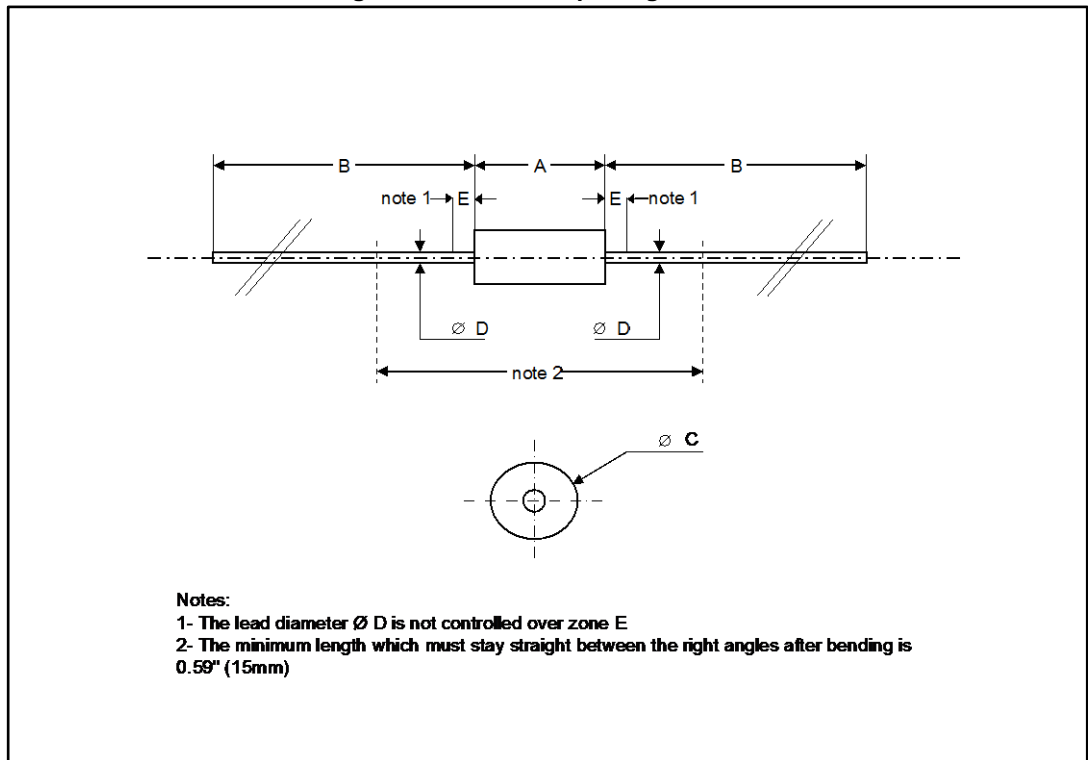


Table 6: DO-201AD package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		9.5		0.3740
B	25.4		1.000	
C		5.3		0.2087
D		1.3		0.0512
E		1.25		0.0492

3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH4L06	STTH4L06	DO-201AD	1.16 g	600	Ammopack
STTH4L06RL	STTH4L06			1900	Tape and reel

4 Revision history

Table 8: Document revision history

Date	Revision	Changes
22-Sep-2009	1	First issue.
27-Jan-2017	2	Removed DO-15 package.

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